

11/30/99

JC377 U.S. PTO

Atty. Docket No. AMAT/4285/MD/PVD/DV

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application
 Commissioner of Patents and Trademarks
 Washington, D.C. 20231

JC525 U.S. PTO
 09/451628
 11/30/99

Re: Inventor(s): AVI TEPMAN, CRAIG B. TODD, JAMES E. YU, DAEHWAN D. KIM, CHRIS BUCHNER,
 and SHIV KUMAR
 Title: INTEGRATED MODULAR PROCESSING PLATFORM

Transmitted herewith is the patent application identified above, including:

Specification, claims and abstract, totaling 46 pages.
 Drawings totaling 31 pages, Formal Informal.
 Executed Declaration and Power of Attorney.
 Information Disclosure Statement w/ Form 1449 and References.
 Assignment of the invention to **Applied Materials, Inc.**

Assignment Recordation Cover Sheet

FEE CALCULATION

Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	6	-20=	0	x \$18.00	0.00
Independent Claims	5	-3=	2	x \$78.00	156.00
Basic Filing Fee				\$760.00	\$760.00
TOTAL FEES					\$916.00

The Commissioner is hereby authorized to charge \$ _____ to Deposit Account No. _____.

The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. _____. A duplicate copy of this transmittal is enclosed.

Please address all future correspondence to:

**PATENT COUNSEL
 APPLIED MATERIALS, INC.
 Legal Affairs Department
 P.O.BOX 450A
 Santa Clara, CA. 95052**

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231.

Express Mail Receipt No. EL422319741US

Date of Deposit 30 November, 1999

Signature B. Todd Patterson

Respectfully submitted,


 B. Todd Patterson
 Registration No. 37,906